



Process Change Notification Form

PCN Number:	PCN_0234																					
Date of Notification:	08/01/2008																					
Cirrus Logic P/N(s):	EP9307-CR, EP9307-CRZ, EP9307-IR, EP9307-IRZ																					
Date PCN Effective:	11/01/2008																					
Reason for Change:	<input type="checkbox"/> Design /New Rev. <input type="checkbox"/> Fab Site <input type="checkbox"/> Fab Process <input type="checkbox"/> Additional Fab Source <input type="checkbox"/> Assembly Site <input type="checkbox"/> Assembly Process <input checked="" type="checkbox"/> Additional Assembly Source <input type="checkbox"/> Other (specify)																					
Description of Change:	<input type="checkbox"/> Fix errata <input type="checkbox"/> Yield enhancement <input type="checkbox"/> Fix known bug <input type="checkbox"/> Performance Improvement <input checked="" type="checkbox"/> Other:																					
	<p>Cirrus Logic intends to introduce Siliconware, Taiwan (SPIL) as an additional assembly site for the EP9307 family of products. These products are currently assembled at STATS-ChipPAC, Shanghai. Addition of Siliconware will result in increased manufacturing capacity and flexibility to support customer demand.</p>																					
	<p>Summary of Bill of Materials Change for EP9307-CRZ and EP9307-IRZ</p> <table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th></th> <th>STATS-ChipPAC, Shanghai</th> <th>Siliconware</th> </tr> </thead> <tbody> <tr> <td>Substrate</td> <td>2-layer</td> <td>2-Layer</td> </tr> <tr> <td>Die Attach</td> <td>Ablestik 2000B</td> <td>Ablestik 2000</td> </tr> <tr> <td>Mold Compound</td> <td>Sumitomo G770LC</td> <td>Nitto GE-100LFCS</td> </tr> <tr> <td>Bond Wire</td> <td>1.0 mil Au</td> <td>0.8 mil Au / Pd 2N</td> </tr> <tr> <td>Solder Spheres</td> <td>Sn/Ag/Cu</td> <td>Sn/Ag/Cu</td> </tr> <tr> <td>Mark Format</td> <td>242 Rev B</td> <td>242 Rev B</td> </tr> </tbody> </table>		STATS-ChipPAC, Shanghai	Siliconware	Substrate	2-layer	2-Layer	Die Attach	Ablestik 2000B	Ablestik 2000	Mold Compound	Sumitomo G770LC	Nitto GE-100LFCS	Bond Wire	1.0 mil Au	0.8 mil Au / Pd 2N	Solder Spheres	Sn/Ag/Cu	Sn/Ag/Cu	Mark Format	242 Rev B	242 Rev B
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	Case outline and board level footprint will not be affected.																					
Cirrus Logic P/N Change:	<input type="checkbox"/> Yes, New Part Number: <input checked="" type="checkbox"/> No																					

<p>Pack Mark Change:</p>	<p><input checked="" type="checkbox"/> Yes <input type="checkbox"/> No If Yes, briefly explain:</p> <p>Parts assembled at STATS-ChipPAC-Shanghai carry a 12 character traceability code of: FFBARRLLYYWW.</p> <p>Parts assembled at Siliconware will display a 12 character Pack Mark of: FFWARLLYYWW.</p> <p>Where: FF = 2 character field denoting wafer fab RR = 2 character field denoting device revision LL = 2 character field denoting the lot ID code YY = 2 character field denoting the year of manufacture WW = 2 character field denoting the work week of manufacture</p> <p>Mark Format / Layout will not be affected by this site addition</p>
<p>Lot Effective Date:</p>	<p>11/01/2008 <i>[Contact the area sales representative for availability of samples if applicable]</i></p>
<p>Quality & Reliability impact:</p>	<p>None Qualification Data: <input checked="" type="checkbox"/> Required <input type="checkbox"/> Not Required *See pages below*</p>
<p>Datasheet Change Required?</p>	<p><input type="checkbox"/> Yes <input checked="" type="checkbox"/> No If Yes, briefly explain:</p>
<p>Software Change Required?</p>	<p><input type="checkbox"/> Yes <input checked="" type="checkbox"/> No If Yes, briefly explain:</p>



RELIABILITY QUALIFICATION REPORT

Report Date: 7/29/2008

Page 1 of 1

Job #: QJ1540

Subject/Purpose:

This is to qualify the 272TFBGA Pb and Pb-free packages assembled at Siliconware (Taiwan).

APPROVALS:

Rod Boutwell
Reliability Engineering

Results:

Qualification successful.

STATUS:

Complete - Pass

<u>Stress</u>	<u>Conditions</u>	<u>Method</u>	<u>Duration</u>	<u>Lot</u>	<u>Results (Fail/Sample)</u>
Precondition MSL-3	24HR 125 °C Bake 192HR 30°C/60%RH Soak 3 pass 260 °C Convection reflow	JESD22-A113	Precondition	1	0/231
THB	85 °C 85 %RH 2.0 Volts	JESD22-A101	500 Hours 1000 Hours	1 1	0/77 0/77
Temperature Cycle cond. B	-55 °C +125 °C air to air	JESD22-A104	1000 Cycles	1	0/77
Tomography (CSAM)		J-STD-035	Post Temp Cycle	1	0/11
Unbiased HAST	130 °C 85 %RH	JESD22-A118	96 Hours	1	0/77
HTSL (High Temp Storage Life)	150 °C	JESD22-A103	500 Hours 1000 Hours	1 1	0/77 0/77

Background Information:

Part #: EP9407	Rev: A1	Fab: UMC - 8F	Lead Finish: _
Package: 272TFBGA	Assembly: Siliconware (Taiwan)		Start Date: 12/19/2007

Prepared by: Rod Boutwell

CONFIDENTIAL

Cirrus Logic PCN administrator: _____

Acknowledgement of Receipt of Notice:

Does customer waive PCN Effective Date? YES NO

Company Name: _____

Name (please print): _____ Title: _____

Signature: _____ Date: _____

Customer Representative is to obtain the customer acknowledgement/signature and return this notification to Cirrus Logic Corp. Quality, attn: PCN administrator at fax number (512) 851-4656

***NOTE: Lack of acknowledgement within 30 days of the date of notice, constitutes acceptance of change.
(Reference JEDEC Industry Standard: JESD-46)***